



WANSEMI
万芯半导体

WP1002

Enhancement Mode N-Channel Power MOSFET

SOT23/NMOS/100V/ $\pm 20V$ /1.5V/2.3A/200m Ω

Rev1.1

100V,200mΩ,2.3A, Fast Switching N-Channel

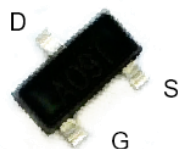
1.Features

- ◆ Green Device Available
- ◆ Super Low Gate Charge
- ◆ Fast switching
- ◆ $V_{GS} \pm 20V$

V_{DS}	$R_{DS(on)}$ Typ.	I_D Max.
100V	200mΩ @ 10V	2.3A
	230mΩ @ 4.5V	

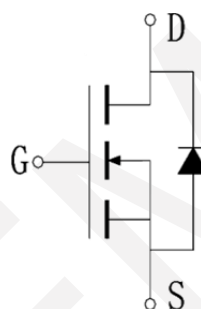
2.Applications

- ◆ Power Switching Application
- ◆ Load Switching



SOT23

Pin Description



Schematic Diagram

3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP1002	MA4	SOT23	3,000	180,000

4.Absolute Max Ratings at $T_a=25^{\circ}C$ (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V_{DSS}	100	V
Gate to Source Voltage	V_{GSS}	± 20	V
Drain Current (DC)	I_D	2.3	A
Drain Current (Pulse), $PW \leq 300\mu s$	I_{DP}	5	A
Total Dissipation	P_D	1	W
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to +150	$^{\circ}C$

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5.Thermal Resistance Ratings (Note 2)

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	125	$^{\circ}C/W$
Thermal Resistance Junction-Case	$R_{\theta JC}$	80	$^{\circ}C/W$

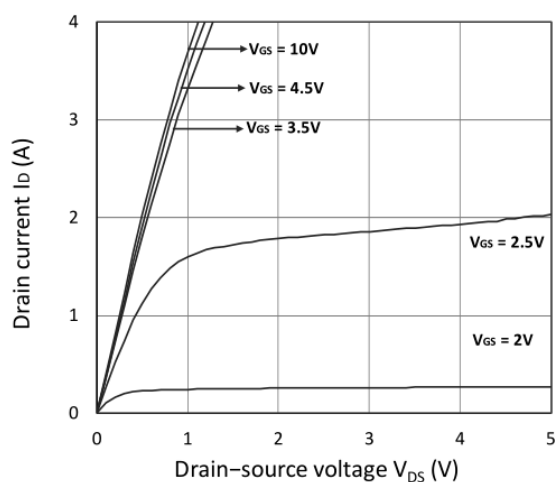
Note 2: When mounted on 1 inch square copper board $t \leq 10sec$ The value in any given application depends on the user's specific board design.

6. Electrical Characteristics at Ta=25°C (Note 3)

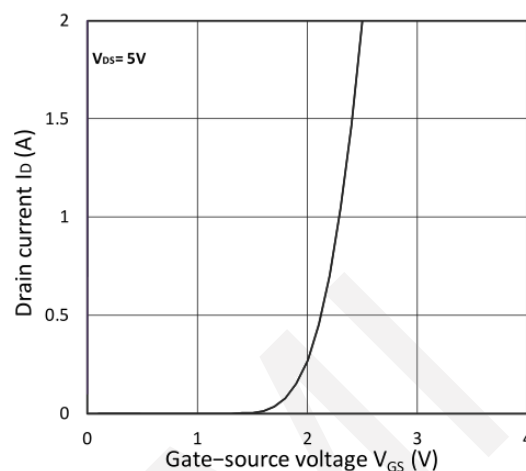
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	100			V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$			1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.1	1.5	2.5	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 2A, V_{GS} = 10V$		200	280	m Ω
		$I_D = 1.5A, V_{GS} = 4.5V$		230	310	m Ω
Input Capacitance	C_{iss}	$V_{GS}=0V,$ $V_{DS}=50V,$ Frequency=1.0MHz		440		pF
Output Capacitance	C_{oss}			14		pF
Reverse Transfer Capacitance	C_{rss}			10		pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DD} = 50V, I_D = 2A$ $V_{GS} = 10V, R_G = 1\Omega$		14		ns
Rise Time	t_r			54		ns
Turn-OFF Delay Time	$t_{d(off)}$			18		ns
Fall Time	t_f			11		ns
Total Gate Charge	Q_g	$V_{DS} = 50V,$ $V_{GS} = 10V,$ $I_D = 2A$		5.3		nC
	Q_{gs}			1.4		nC
	Q_{gd}			1.8		nC
Diode Forward Voltage	V_{FSD}	$I_S = 1A, V_{GS} = 0$			1.2	V

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

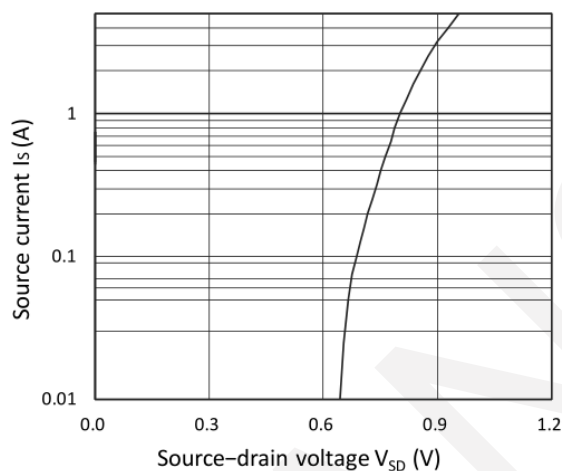
7. Typical Electrical and Thermal Characteristics



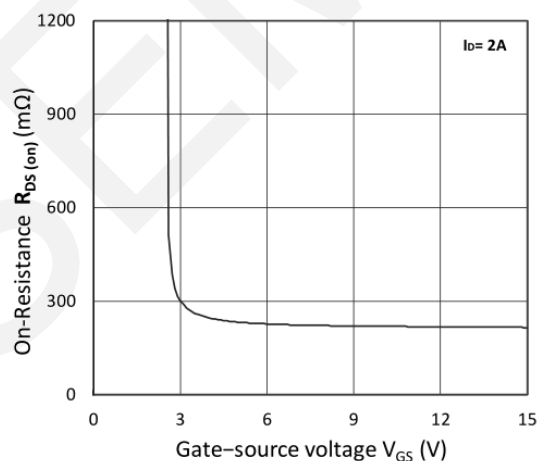
Output Characteristics



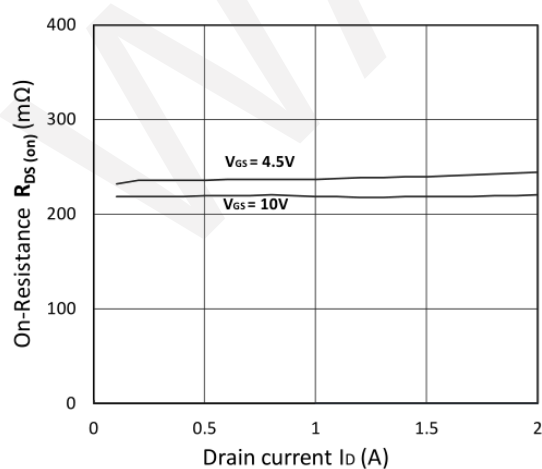
Transfer Characteristics



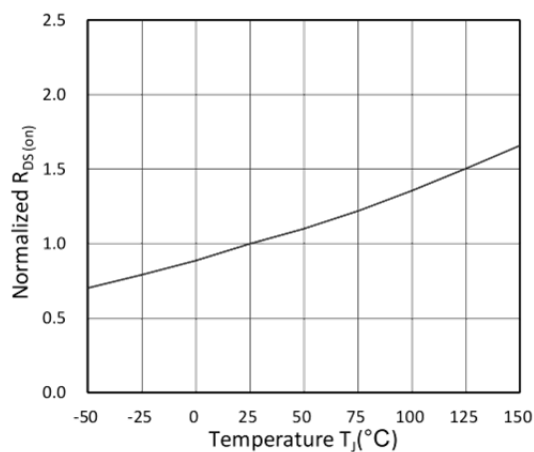
Forward Characteristics of Reverse



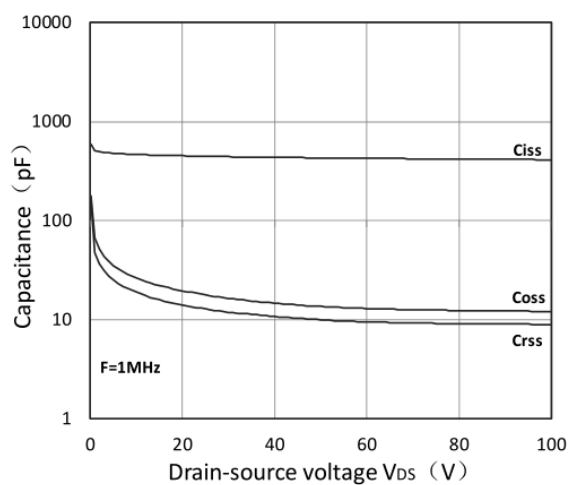
$R_{DS(ON)}$ vs. V_{GS}



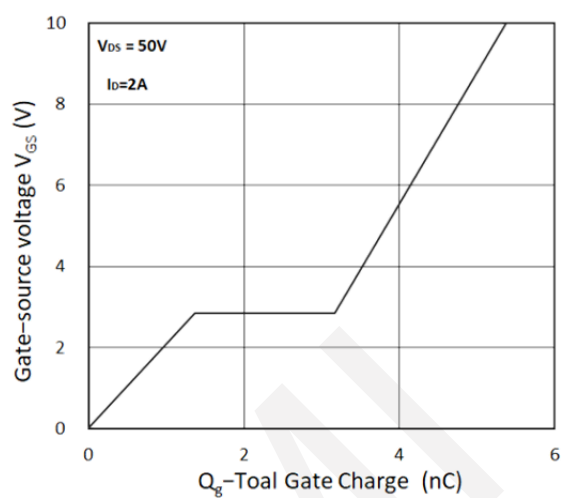
$R_{DS(ON)}$ vs. I_D



Normalized $R_{DS(on)}$ vs. Temperature

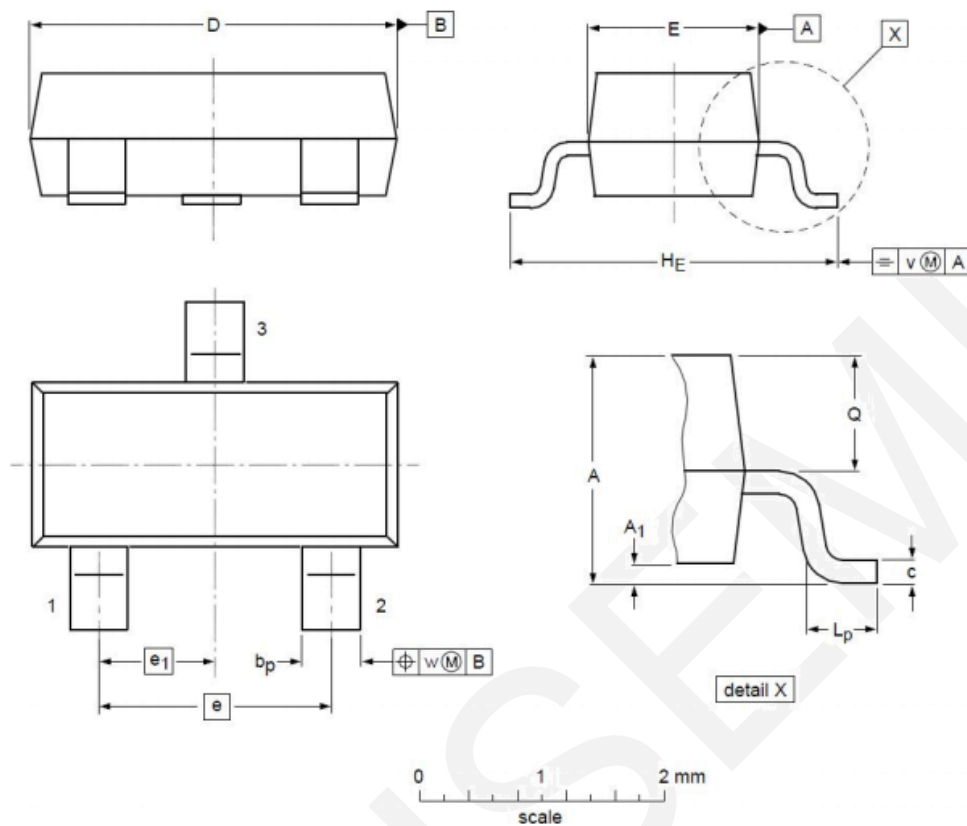


Capacitance Characteristics



Gate Charge Characteristics

8.Package Dimensions



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A ₁	0.01	0.05	0.10
b _p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e ₁	--	0.95	--
H _E	2.25	2.40	2.55	L _p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

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